

Title (en)
EMI-SHIELDING GASKET.

Title (de)
DICHTUNG ZUR ABSCHIRMUNG GEGEN ELEKTROMAGNETISCHE STÖRUNGEN.

Title (fr)
JOINTS DE PROTECTION PAR BLINDAGE CONTRE DES INTERFERENCES ELECTROMAGNETIQUES.

Publication
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Application
EP 94901671 A 19931123

Priority

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- US 98127592 A 19921125
- US 98161892 A 19921125

Abstract (en)
[origin: WO9413123A1] A gasket (10) for shielding electromagnetic interference passing through a seam between two electrically conductive bodies includes an EMI shield (14) embedded in a resilient foam profile (12) for shielding electromagnetic interference passing through the seam. The gasket further includes a seamless, electrically conductive skin (16) covering at least part of the outer surface of the foam profile (12). The skin (16) is arranged so that electric charge which accumulates on the EMI shield (14) can be dissipated to ground. Another gasket includes a base for securing the gasket to the first, electrically conductive body and a multiplicity of discrete, elongate, metallized filaments projecting from the base so that a substantial amount of the filaments contacts the second, electrically conductive body when electromagnetic interference passing through a seam between the bodies is to be shielded. The gasket further includes structure, arranged with the base, so that energy absorbed by the shielding member as a result of the shielding of passing electromagnetic interference can be dissipated to ground through the first, electrically conductive body.

IPC 1-7
H05K 9/00

IPC 8 full level
H05K 9/00 (2006.01)

CPC (source: EP)
H05K 9/0015 (2013.01)

Citation (search report)
See references of WO 9413123A1

Citation (examination)

- PATENT ABSTRACTS OF JAPAN, unexamined applications, M section, vol. 11, no.
- 120, 15 April 1987 THE PATENT OFFICE JAPANESE GOVERNMENT page 35 M 580; & JP,A, 61-261 013 (HITACHI) 19 November 1986 (19.11.86)

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